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**Takahashi et al.**

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(54) **SEMICONDUCTOR MODULE**

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(52) **U.S. Cl.**  
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(58) **Field of Classification Search**  
USPC ..... D13/110, 182, 184; 174/250, 253;  
257/666, 668, 678, 690, 694, 696;  
361/713, 728, 736, 775  
See application file for complete search history.

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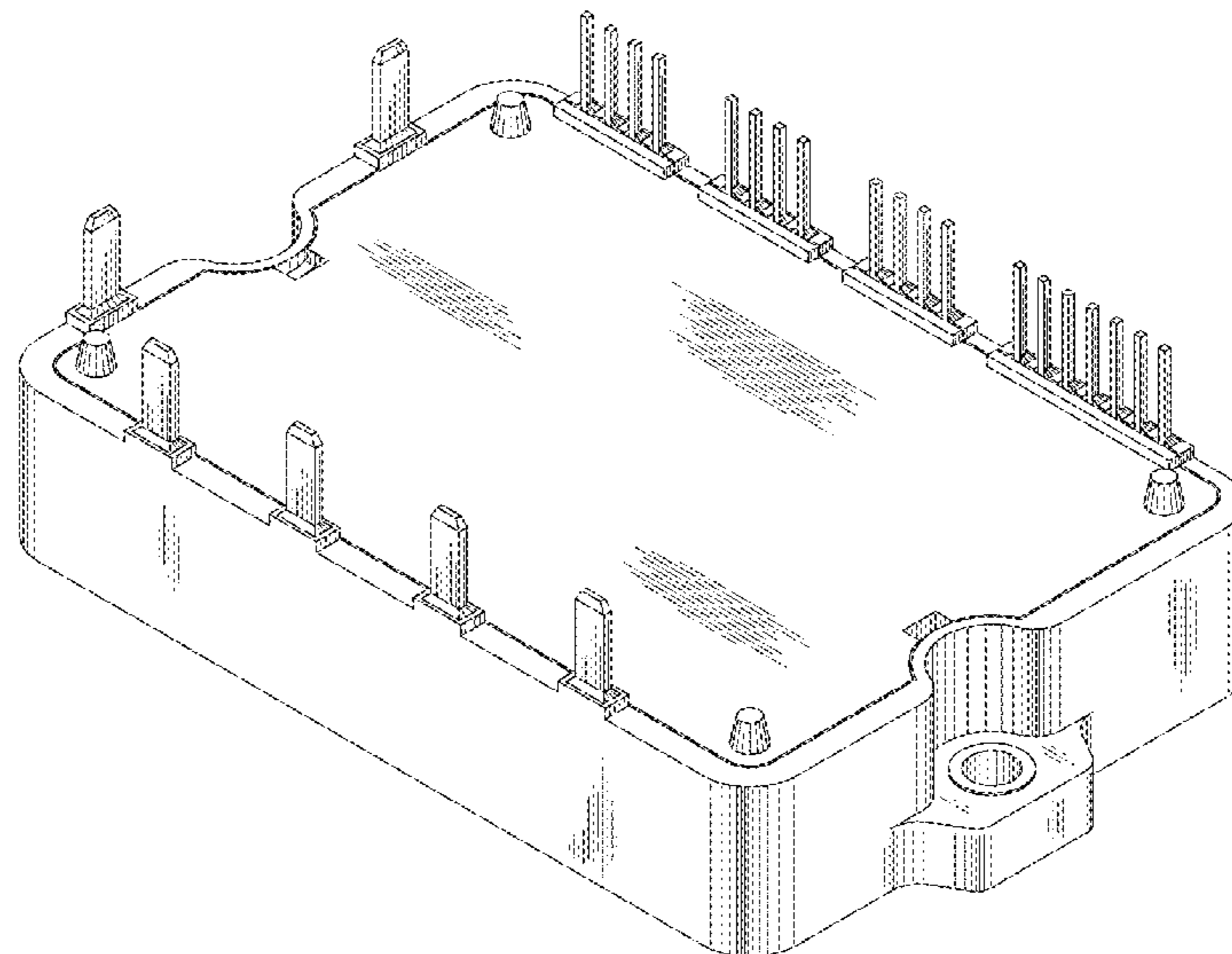
(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

**DESCRIPTION**

FIG. 1 is a front view of a semiconductor module according to our new design;  
FIG. 2 is a rear view of the semiconductor module of FIG. 1;  
FIG. 3 is a left side view of the semiconductor module of FIG. 1;  
FIG. 4 is a right side view of the semiconductor module of FIG. 1;  
FIG. 5 is a top view of the semiconductor module of FIG. 1;  
FIG. 6 is a bottom view of the semiconductor module of FIG. 1; and,  
FIG. 7 is a top, front, right side perspective view of the semiconductor module of FIG. 1.  
The ornamental design of the present disclosure is a semiconductor module on which power semiconductor elements and the like may be mounted.

**1 Claim, 7 Drawing Sheets**



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Fig. 1

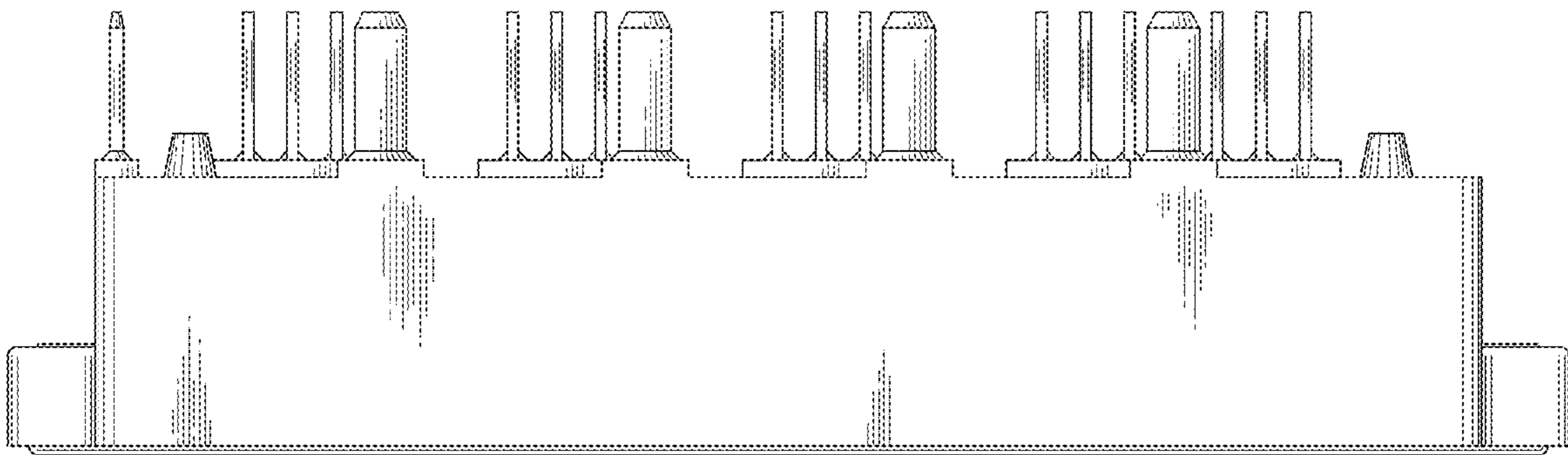


Fig. 2

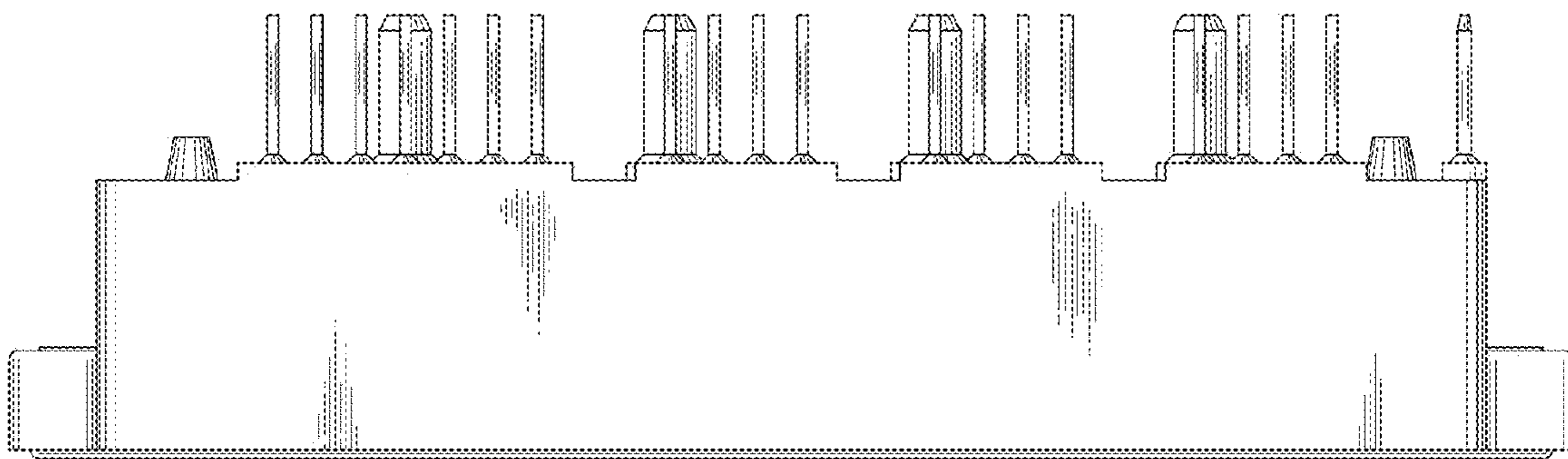


Fig. 3

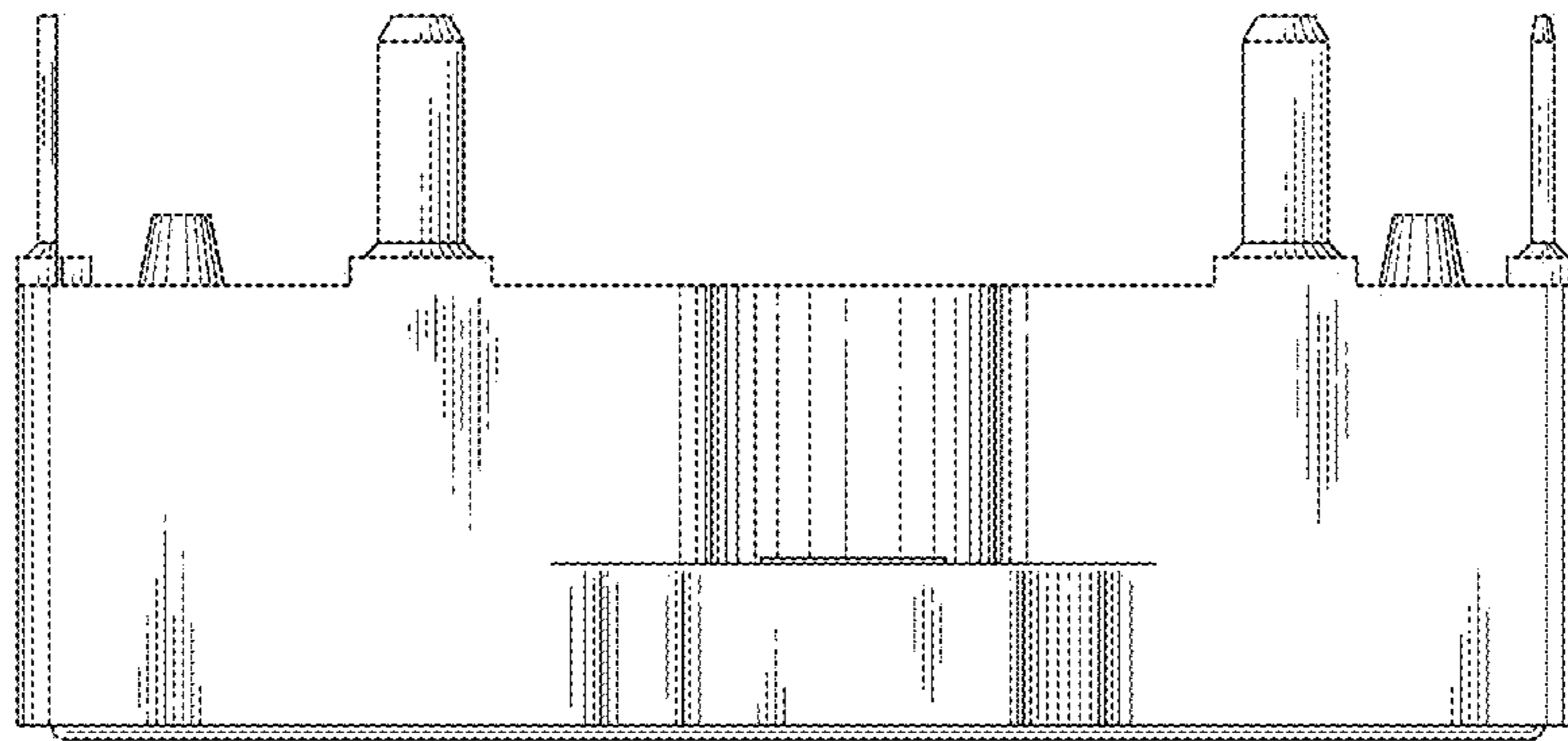


Fig. 4

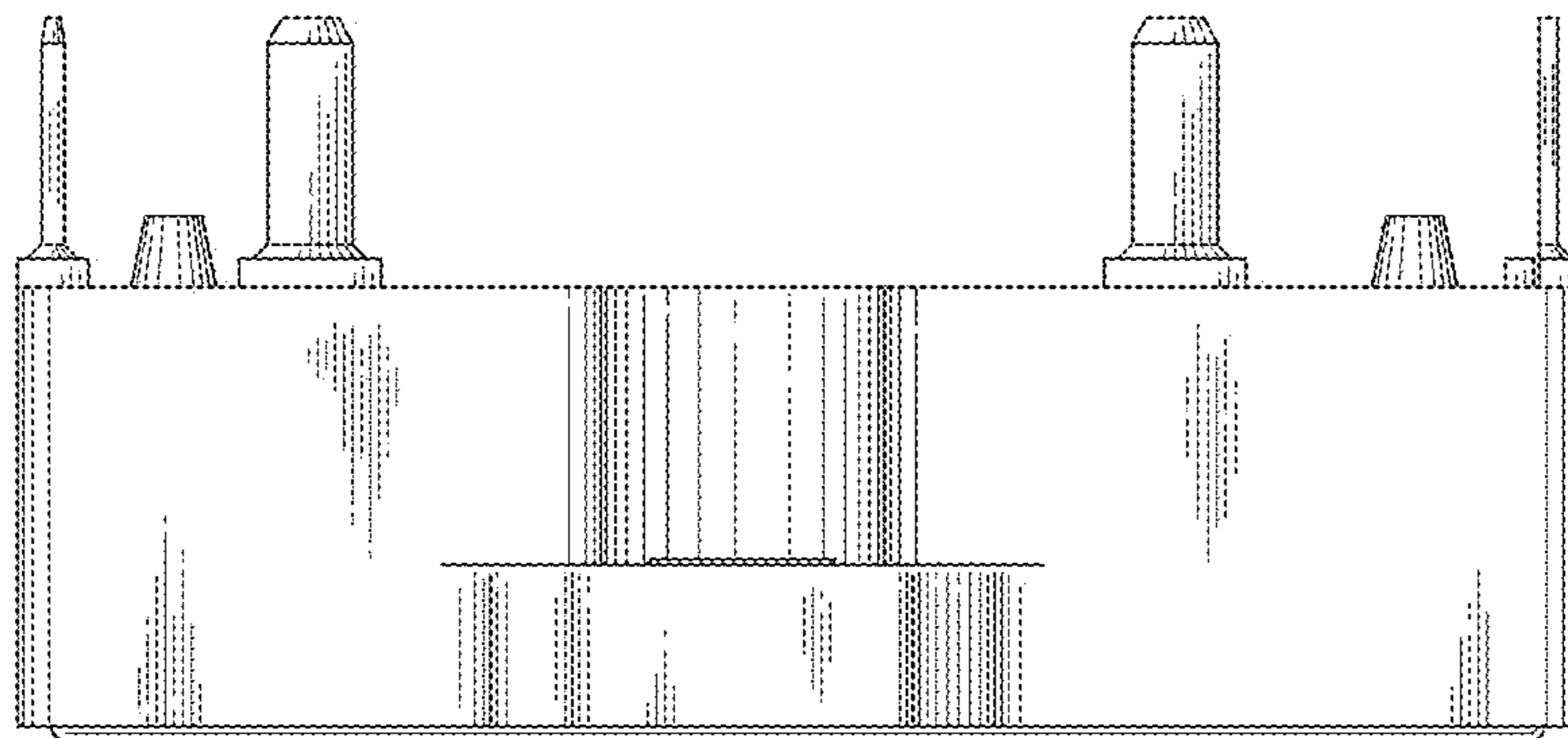


Fig. 5

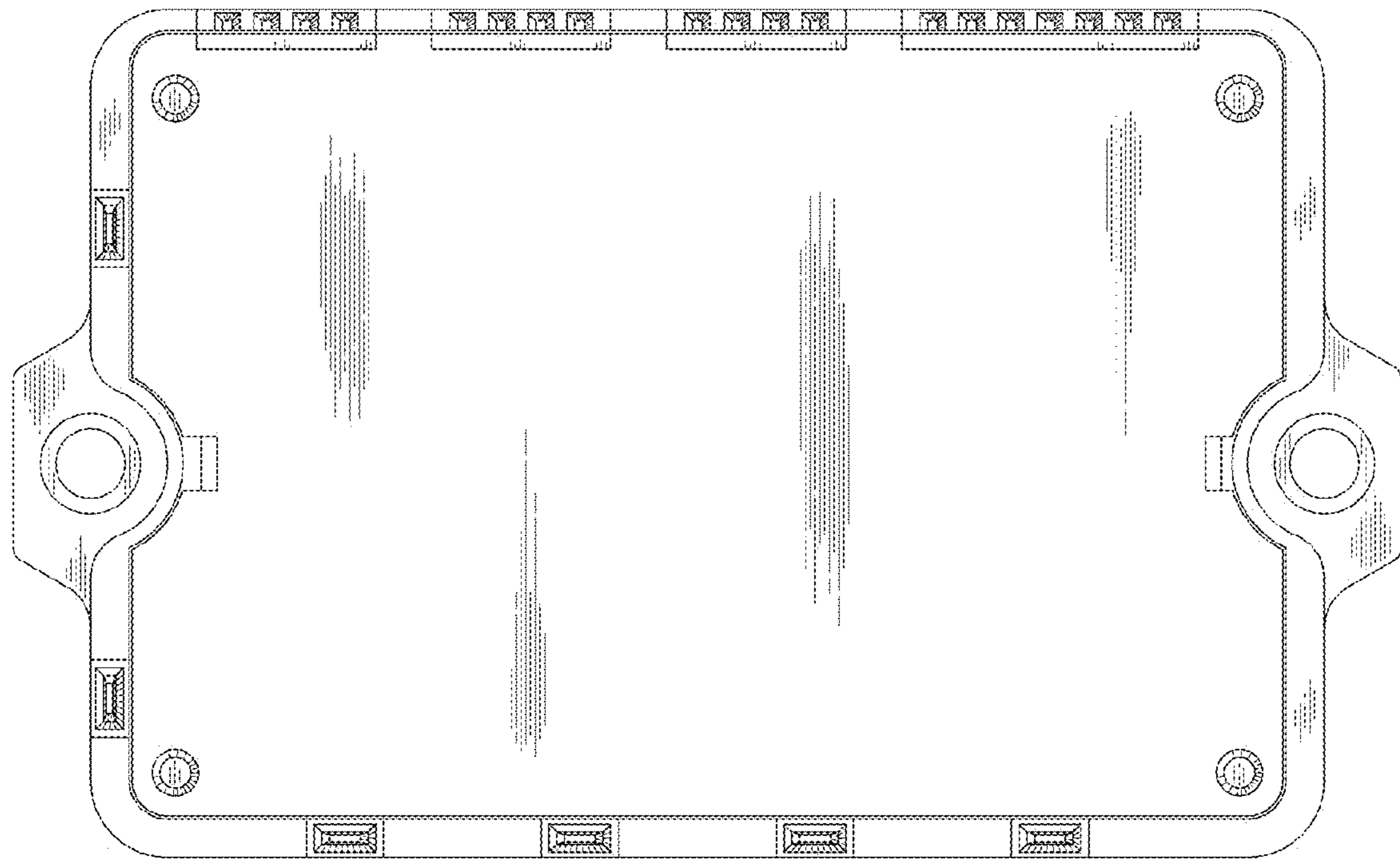


Fig.6

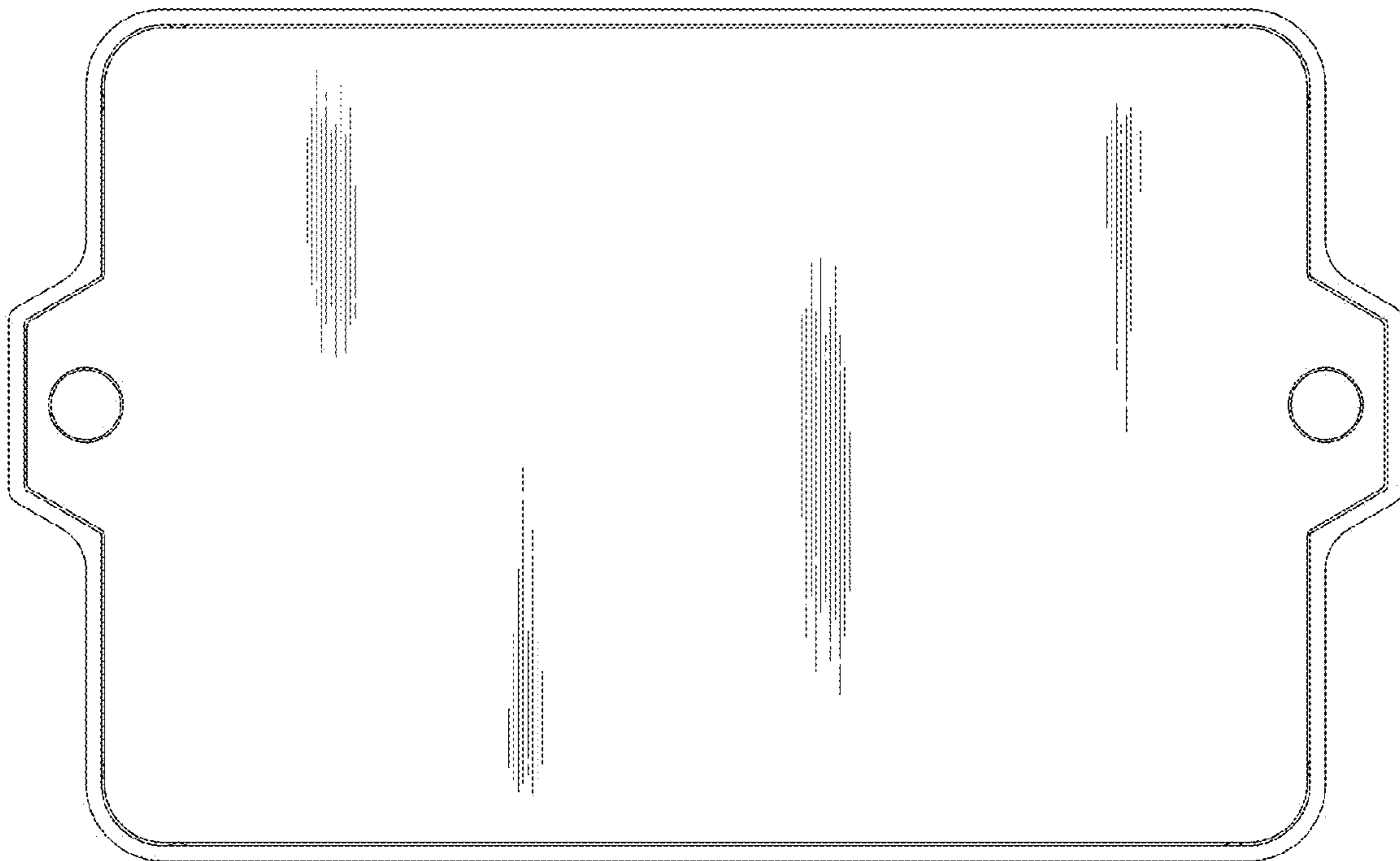




Fig. 7

